ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. Il international and Pan	PC, Bannock	burn, Illinois. A	ll rights reserved ur ntions.	nder both	This docum level parts, t	ent is a decla	ration of the	e substances sses all lowe	within the man r level materia	nufacturer liste ls for which th	ed item. N e manufa	Note: if the acturer has	e item is an asso s engineering re	embly with lower esponsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information				
Supplier Information															
Company name*	Company uni	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2025-09-15				
Contact Name Tit			Title - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative* Title			Fitle - Representative			Phone - Representative*				Ema	Email - Representative*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Proc	Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective D	ate Versio	on 1	Manufacturing Site		Weigh	nt*	UOM	Unit Type	
	NVMJS G	T3D3N04CTX	TRENCH 6 40V LFPAK 5x7			2025-09-15		]	PBB		116.8	14644	mg	Each	
Manufacturing Proccess Informat	ion														
Terminal Plating / Grid Array Ma	terial	Terminal Base A	Alloy J.	-STD-020 MS	020 MSL Rating		Peak Process Body Tem		ature Max Time at Peak Te		Semperature Number of Reflow Cycles		es		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1				260		C	30	se	conds	nds 3			
Comments															
evel 1 - maximum time at peak temperatu	re during so	oldering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	7.10649	mg	Supplier	Iron (Fe)	7439-89-6		0.0071	mg
			Supplier	Copper (Cu)	7440-50-8		7.0973	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0021	mg
Die	0.808	mg	Supplier	Silicon (Si)	7440-21-3		0.808	mg
Die Attach Solder	5.71472	mg	Supplier	Silver (Ag)	7440-22-4		0.1429	mg
			А	Lead (Pb)	7439-92-1	7a	5.2861	mg
			Supplier	Tin (Sn)	7440-31-5		0.2857	mg
Lead Frame	46.4752	mg	Supplier	Silver (Ag)	7440-22-4		0.3021	mg
			Supplier	Iron (Fe)	7439-89-6		0.0465	mg
			Supplier	Copper (Cu)	7440-50-8		46.1127	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0139	mg
Mold Compound-Black	52.562	mg	Supplier	Polymer 1,1'-biphenyl with formaldehyde and Phenol, glycidyl ether	1201169-35-8		2.6281	mg
			Supplier	Polycondensate of 4,4'- bis(methoxymethyl)biphenyl and phenol	205830-20-2		1.3141	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2628	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.357	mg
Plating	4.11329	mg	Supplier	Palladium (Pd)	7440-05-3		0.3229	mg
			В	Nickel (Ni)	7440-02-0		3.7452	mg
			Supplier	Gold (Au)	7440-57-5		0.0452	mg
Wire Bond	0.034944	mg	Supplier	Palladium (Pd)	7440-05-3		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0346	mg